

FIG. 1

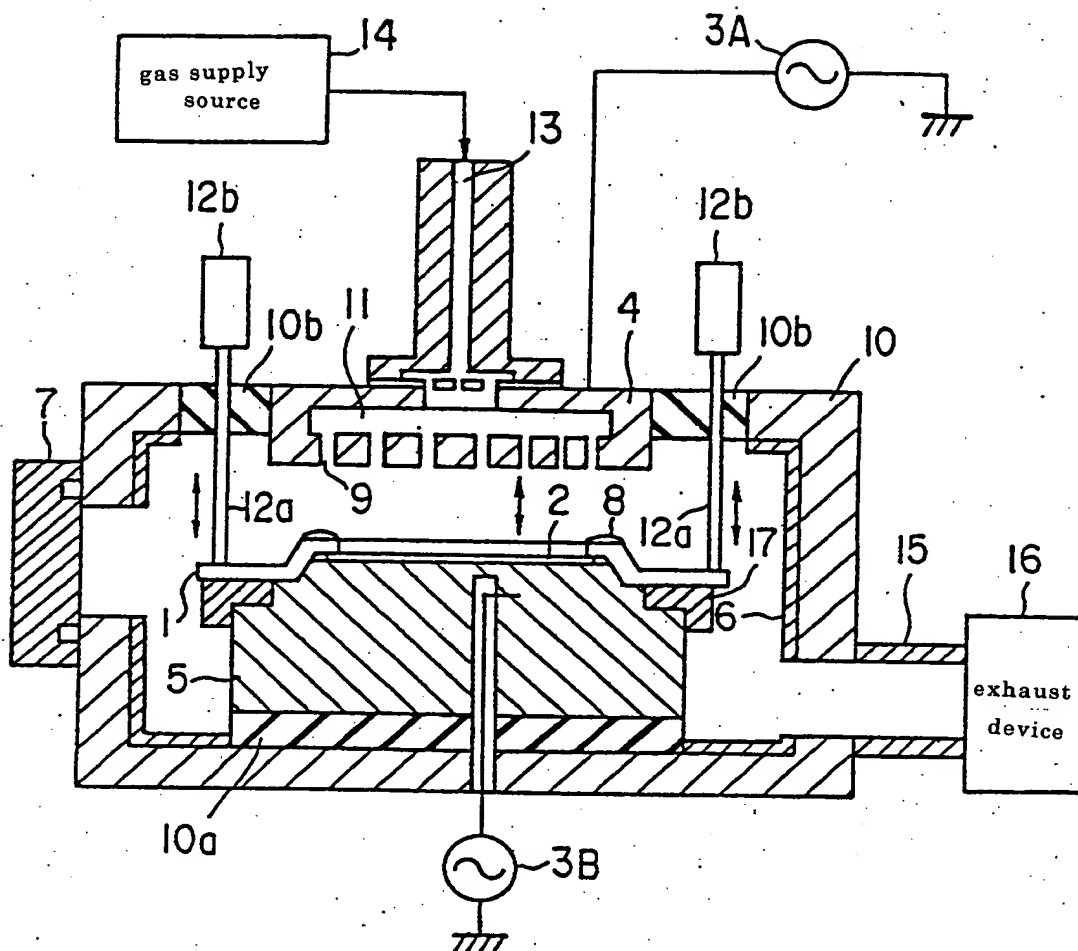
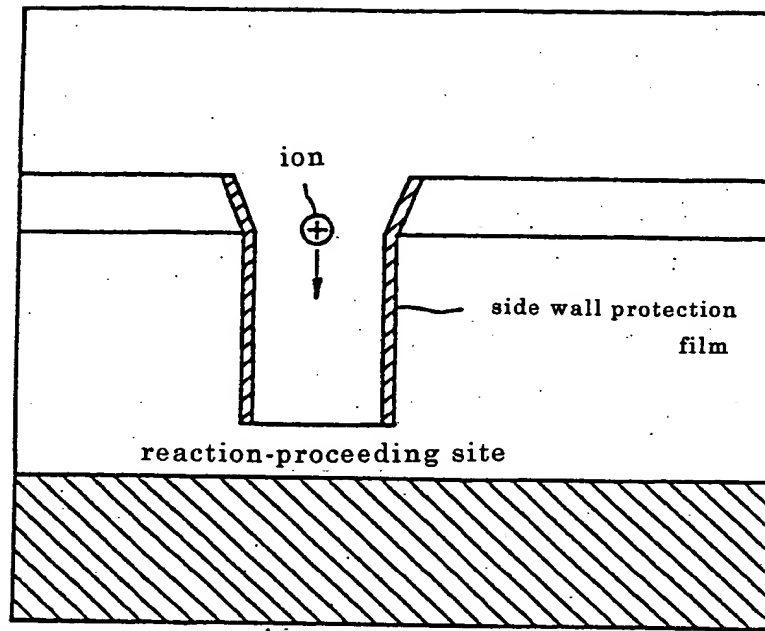
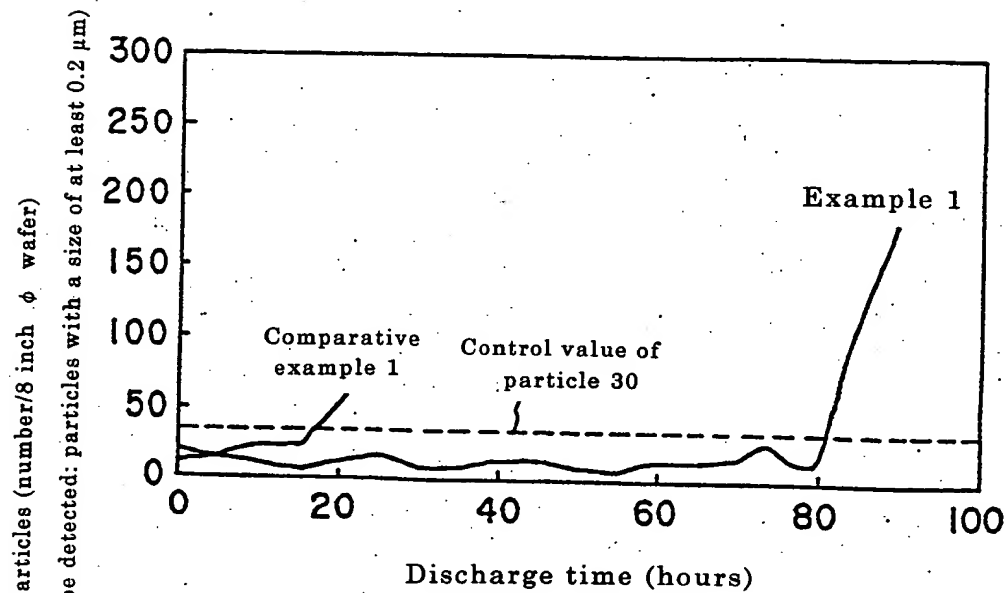


FIG. 2



processing method of a high aspect ratio

FIG. 3



Variation in the number of particles deposited on wafer
in relation to discharge time

FIG. 4

